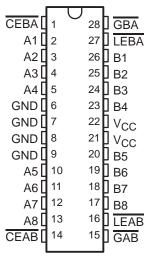
SCAS136 - D3608, JULY 1990 - REVISED APRIL 1993

- Inputs Are TTL-Voltage Compatible
- 3-State True Outputs
- Back-to-Back Registers for Storage
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC[™] (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C

description

This 8-bit registered transceiver contains two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch enable (LEAB or LEBA) and output enable (GAB or GBA) inputs are provided for each register to permit independent control in either direction of data flow.

DW PACKAGE (TOP VIEW)



The A-to-B enable (CEAB) input must be low in order to enter data from A or to output data to B. Having CEAB low and LEAB low makes the A-to-B latches transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and GAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B-to-A is similar, but requires the use of CEBA, LEBA, and GBA inputs.

The 74ACT11543 is characterized for operation from -40° C to 85°C.

FUNCTION TABLE

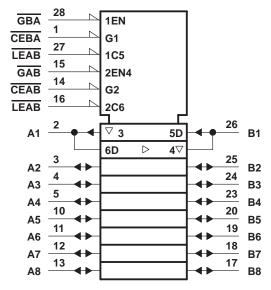
	INPUTS		LATCH STATUS	OUTPUT BUFFERS
CEAB	LEAB	GAB	A TO BT	B1 THRU B8
Н	Х	Х	Storing	Z
Х	Н		Storing	
Х		Н		Z
L	L	L	Transparent	Current A Data
L	Н	L	Storing	Previous [‡] A Data

[†] A-to-B data flow is shown: B-to-A flow control is the same except uses CEBA, LEBA, and GBA.

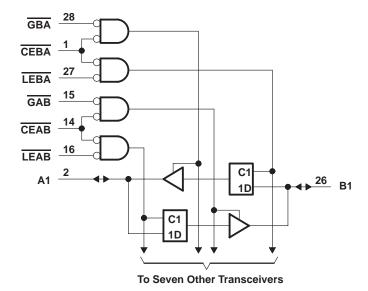
EPIC is a trademark of Texas Instruments Incorporated.

[‡] Data present before low-to-high transition of LEAB.

logic symbol†



logic diagram (positive logic)



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Output voltage range, VO (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	± 50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	$\dots \dots \pm 50 \text{ mA}$
Continuous current through V _{CC} or GND	$\dots \dots \pm 200 \text{ mA}$
Storage temperature range	65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
VI	Input voltage	0		VCC	V
Vo	Output voltage	0		VCC	V
loh	High-level output current			-24	mA
lOL	Low-level output current			24	mA
Δt/Δν	Input transition rise or fall rate	0		10	ns/V
TA	Operating free-air temperature	- 40		85	°C



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electrical characteristics over recommended operating free-air temperature range

	ARAMETER	TEST CONDITIONS	Vaa	T,	_Δ = 25°C	;	MIN	MAX	UNIT			
	ARAIVIETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	IVIIIV	IVIAA	UNIT			
		ΙΟΗ = – 50 μΑ	4.5 V	4.4			4.4					
		ΙΟΗ = - 30 μΑ	5.5 V	5.4			5.4					
VOH		10.1 - 24 mA	4.5 V	3.94			3.8		V			
		I _{OH} = -24 mA	5.5 V	4.94			4.8					
		I _{OH} = -75 mA [†]	5.5 V				3.85					
		I _{OL} = 50 μA				0.1		0.1				
		IOL = 50 μΑ	5.5 V			0.1		0.1				
VOL		Jan 24 mA	4.5 V			0.36		0.44	0.44 V 0.44 1.65			
		I _{OL} = 24 mA	5.5 V			0.36		0.44				
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65				
Ιį	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		± 1	μΑ			
loz	A or B ports‡	$V_O = V_{CC}$ or GND	5.5 V			± 0.5		± 5	μΑ			
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ			
Δlcc	§	One input at 3.4 V, Other inputs at GND or V _{CC}				0.9		1	mA			
Ci	Control inputs				4.5				pF			
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12				pF			

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			$T_A = 2$	25°C	MIN	MAX	UNIT
			MIN	MAX	IVIIIV		UNIT
t _W	Pulse duration, LEAB or LEBA low		4		4		ns
	Setup time	Data after LEAB or LEBA↑					
tsu	Setup time	Data before CEAB or CEBA↑			3		ns
4.	Hold time	Data after LEAB or LEBA↑	2		2		20
th	riola line	Data after CEAB or CEBA↑	1.5		1.5	·	ns



[‡] For I/O ports, the parameter I_{OZ} includes the input leakage current.

[§] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or VCC.

74ACT11543 OCTAL REGISTERED TRANSCEIVER WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

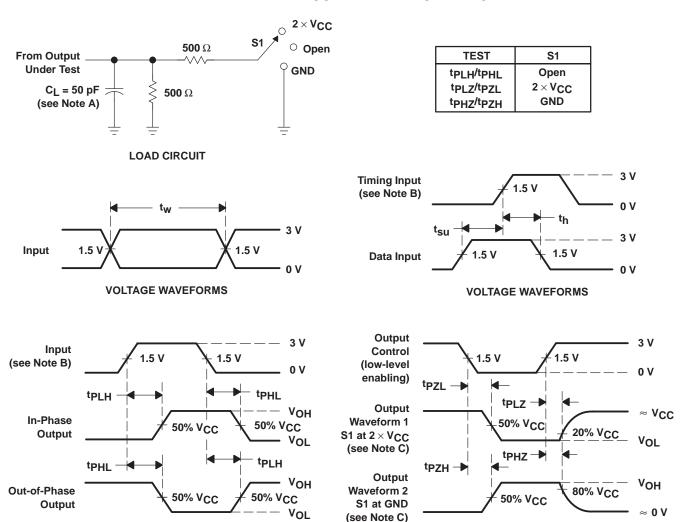
PARAMETER	FROM	то	T,	4 = 25°C	;	MIN	MAX	UNIT
FARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIV	IVIAA	ONIT
^t PLH	A or B	B or A	3.5	6.2	9.1	3.5	10.2	ns
^t PHL	AOIB	BOIA	3.2	6.5	10.8	3.2	12.1	115
^t PLH	LEBA or LEAB	A or B	3	6.1	10.1	3	11.2	20
t _{PHL}	LEBA OF LEAB	AUIB	3.7	7.2	11.7	3.7	13.2	ns
^t PZH	CEBA or CEAB	A or B	3.5	6.7	11.1	3.5	12.2	— ns ∣
t _{PZL}	CEBA OF CEAB	AUIB	3.2	8.4	13.4	3.2	16	
^t PHZ	CEDA or CEAD	A or B	4.8	7.3	10.1	4.8	11	ns
t _{PLZ}	CEBA or CEAB	AUIB	5.1	7.5	10.3	5.1	11.1	115
^t PZH	GBA or GAB	A or B	3.3	6.4	10.5	3.3	11.5	20
^t PZL	GBA OF GAB	AUIB	3	8	12.8	3	15.3	ns
^t PHZ	CDA on CAD	A or B	4.6	6.9	9.6	4.6	10.4	—l ns l
tPLZ	GBA or GAB	AUIB	5	7.1	9.8	5	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CON	TYP	UNIT			
C .	Down dissination consistence nor transcriver	Outputs enabled	C: 50 pF	f = 1 MHz	47	pF	
Cpd	Power dissipation capacitance per transceiver	Outputs disabled	$C_L = 50 \text{ pF},$	I = I IVIMZ	13	pr	

VOLTAGE WAVEFORMS

PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

VOLTAGE WAVEFORMS

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ACT11543DWR	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11543DWRE4	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11543DWRG4	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11543NT	OBSOLETE	PDIP	NT	28		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

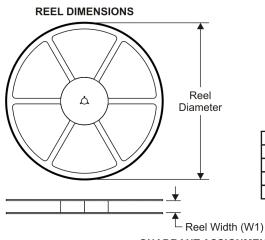
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





Α	0	Dimension designed to accommodate the component width
В	0	Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
٧	٧	Overall width of the carrier tape
ГР	1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT11543DWR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

PACKAGE MATERIALS INFORMATION

11-Mar-2008

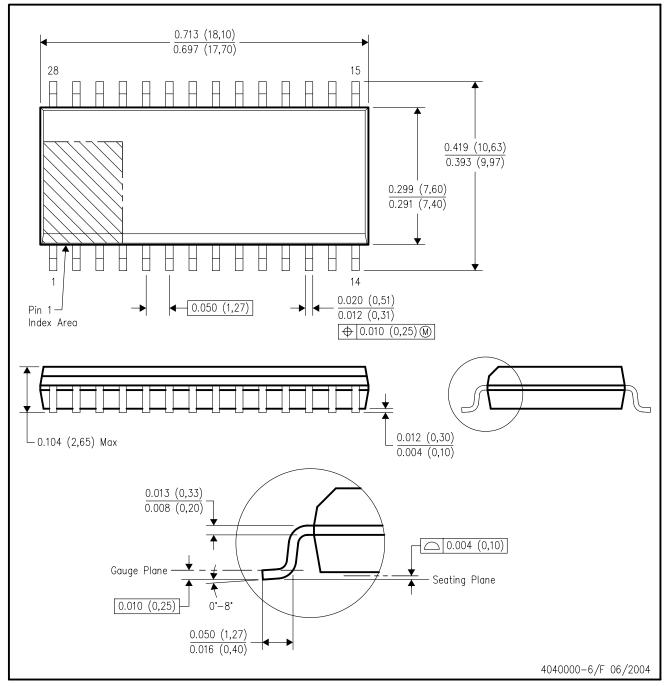


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT11543DWR	SOIC	DW	28	1000	346.0	346.0	49.0

DW (R-PDSO-G28)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AE.

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